

Amendments to the Claims:

Please cancel withdrawn claims 9-21 and 32-36. Please amend claims 1, 7, 22 and 27 as follows. Please add new claims 37-50 as follows.

This listing of claims replaces all prior versions, and listings, of claims in the application.

Listing of claims:

1. (currently amended) A head for polishing a wafer, comprising:
 - a carrier;
 - a retainer ring disposed on a lower edge of said carrier;
 - a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
 - a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes, wherein when a vacuum is applied to the first chamber, and supplied through said first holes and corresponding third holes, a wafer in proximity to the membrane is drawn by the vacuum through the third holes toward said head.
2. (original) The apparatus according to claim 1, wherein an edge of said surface portion of said supporter is chamfered.
3. (original) The apparatus according to claim 1, wherein an edge of said surface portion of said supporter is rounded.
4. (original) The apparatus according to claim 1, wherein said first chamber has a fluid passage communicating external to said polishing head.
5. (original) The apparatus according to claim 1, wherein said second chamber has a fluid

passage communicating external to said polishing head.

6. (original) The apparatus according to claim 1, wherein films are adhered on said flat surface around said first holes, each of said films sized to fit within said third holes.
7. (currently amended) The apparatus according to claim ~~[[1]]~~6, wherein each of said films has a thickness less than that of said membrane.
8. (original) The apparatus according to claim 1, wherein at least one of said second holes penetrates a center portion of said supporter, and for the at least one of said second holes, there is no corresponding hole formed in said membrane.
9. - 21. (canceled)
22. (currently amended) An apparatus for polishing a wafer, comprising:
 - a supporting portion having an abrasive pad disposed thereon;
 - a polishing head disposed over said abrasive pad; and
 - said polishing head comprising:
 - a carrier;
 - a retainer ring disposed on a lower edge of said carrier;
 - a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
 - a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes, wherein when a vacuum is applied to the first chamber, and supplied through said first holes and corresponding third holes,

a wafer in proximity to the membrane is drawn by the vacuum through the third holes toward said head.

23. (previously presented) A head for polishing a wafer, comprising:
 - a carrier having a cavity and a lower edge;
 - a retainer ring disposed at the lower edge of the carrier;
 - a supporter disposed in the cavity of the carrier and configured to provide a first fluid path, the supporter having an outer surface including a plurality of first holes which communicate with the first fluid path; and
 - a membrane enclosing the outer surface of the supporter and having a like plurality of second holes in alignment with the first holes of the supporter, said membrane being spaced apart from the outer surface of the supporter in a first position and abutting the outer surface of the supporter in a second position.
24. (previously presented) The head of claim 23 wherein the first fluid path of the supporter comprises a fluid chamber located in the supporter.
25. (previously presented) The head of claim 23 wherein the second holes of the membrane form a seal about the corresponding first holes of the supporter when the membrane is in the second position.
26. (previously presented) The head of claim 23 further comprising a plurality of film structures, each film structure disposed on the outer surface of the supporter about one of each of the first holes.
27. (currently amended) The head of claim ~~[[27]]~~26, wherein the film structures mate with the second holes of the membrane such that the film structures fit inside the second holes.
28. (previously presented) The head of claim 27, wherein the film structures have a thickness

that is less than a thickness of the membrane.

29. (previously presented) The head of claim 23 further comprising a plurality of third holes formed through the outer surface of the supporter, the plurality of third holes communicating with a second fluid path formed in the supporter.

[[29.]]30. (previously presented) The head of claim 29 wherein the plurality of third holes communicate with an interior region of the membrane between the membrane and the outer surface of the supporter when the membrane is in the second position.

[[30.]]31. (previously presented) The head of claim 23 wherein an edge of the surface portion of the supporter is chamfered.

~~31.-35.~~ 32. - 36. (canceled)

37. (new) A head for polishing a wafer, comprising:
a carrier;
a retainer ring disposed on a lower edge of said carrier;
a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes, wherein films are adhered on said flat surface around said first holes, each of said films sized to fit within said third holes.
38. (new) The apparatus according to claim 37, wherein an edge of said surface portion of said supporter is chamfered.

39. (new) The apparatus according to claim 37, wherein an edge of said surface portion of said supporter is rounded.
40. (new) The apparatus according to claim 37, wherein said first chamber has a fluid passage communicating external to said polishing head.
41. (new) The apparatus according to claim 37, wherein said second chamber has a fluid passage communicating external to said polishing head.
42. (new) The apparatus according to claim 37, wherein each of said films has a thickness less than that of said membrane.
43. (new) The apparatus according to claim 37, wherein at least one of said second holes penetrates a center portion of said supporter, and for the at least one of said second holes, there is no corresponding hole formed in said membrane.
44. (new) A head for polishing a wafer, comprising:
 - a carrier;
 - a retainer ring disposed on a lower edge of said carrier;
 - a supporter disposed in said carrier configured to provide first and second chambers separated from each other, the supporter including a surface portion having a flat surface, a plurality of first holes communicating with said first chamber, and a plurality of second holes communicating with said second chamber; and
 - a membrane enclosing said surface portion of said supporter, said membrane spaced apart from said surface portion, and having a plurality of third holes corresponding to said first holes, wherein at least one of said second holes penetrates a center portion of said supporter, and for the at least one of said second holes, there is no corresponding hole formed in said membrane.

45. (new) The apparatus according to claim 44, wherein an edge of said surface portion of said supporter is chamfered.
46. (new) The apparatus according to claim 44, wherein an edge of said surface portion of said supporter is rounded.
47. (new) The apparatus according to claim 44, wherein said first chamber has a fluid passage communicating external to said polishing head.
48. (new) The apparatus according to claim 44, wherein said second chamber has a fluid passage communicating external to said polishing head.
49. (new) The apparatus according to claim 44, wherein films are adhered on said flat surface around said first holes, each of said films sized to fit within said third holes.
50. (new) The apparatus according to claim 49, wherein each of said films has a thickness less than that of said membrane.